アキシャルリード形セラミックコンデンサ AXIAL LEADED CERAMIC CAPACITORS







特長 FEATURES

- ·汎用型セラミックコンデンサで、単層形と積層形合わせて1pF~10µFと 広い容量範囲で部品の標準化が可能
- ・ラジアルに比べ自挿コストが安く、部品高さ低減、実装密度アップ、在 庫スペースも減少
- ・実装ピッチ5mmから26mmまでジャンパー線機能と兼用可能
- · This widely used ceramic capacitor includes both monolithic and multilayer types to provide a wide capacitance range of 1pF through $10 \,\mu$ F in one standard size and shape.
- · Automatic insertion related costs are lower than with radial type capacitors.
- · Mounting pitch can be between 5mm to 26mm which could be used as a jumper.

用途 APPLICATIONS

- ・Class1品は回路の温度特性補正及び周波数特性の安定化。B、F特はバイ パスコンデンサに最適
- The class 1 temperature compensating (NPO) products can be used in circuits to stabilize frequency and temperature characteristics. • The B, and F dielectrics are optimum for bypass capacitors.

形名表記法 ORDERING CODE 3 5 8 6 定格電圧 [VDC] 公称静電容量 [pF] 容量許容差 梱包 形状寸法(L× ϕ d)〔mm〕 ※R=小数点 4.2×3.2(積層形) 例 ±0.5pF В つづら折り 10 D-075 _ 16 010 袋づめ 3.5×1.9(単層形) J-± 5% С 050 25 1R2 12 K-±10% т 3.2×2.2(積層形) G 35 025 103 10000 M-+20%2.3×2.0(積層形) U 50 Ζ-±20 % 015 3.0×2.5(積層形) 2 4 9 形式 温度特性 リード形状 (mm) 当社管理記号 」 単層標準品 アキシャルリードコンデンサ 0± 250 (ppm /°C) Р CK A-26mmテープ幅テーピング CH 0± 60 (ppm /°C) 52mmテープ幅テーピング 積層標準品 B-△7 RH -220± 60 (ppm /°C) 5.0ピッチフォーミング 積層品(低電圧タイプ) KF $\triangle J$ -750±120 (ppm /°C) △=スペース UJ 7.5ピッチフォーミング KE SL +350~ -1000 (ppm /°C) 単品ストレートリード NA ±10% +30 -85% $\triangle B$ ∴F △=スペース U P 0 5 0 H 1 0 0 J

1		3	
Rated	voltage[VDC]	Outsid	de Dimensions(L $\times \phi$ d) [mm]
L	10	075	4.2×3.2(multilayer type)
E	16		3.5×1.9 (monolithic type)
T	25	050	3.2×2.2 (multilayer type)
G	35	025	2.3×2.0 (multilayer type)
U	50	015	3.0×2.5(multilayer type)
2		4	
Туре		Tem	perature haracteristics
P	Axial leaded capacitors	CK	0± 250 (ppm /°C)
	· · · · ·	CH	0± 60 (ppm /°C)
		RH	-220± 60 (ppm /℃)
		UJ	-750±120 (ppm /℃)
		SL	+350~-1000 (ppm/°C)

△B △F

 $\pm 10\%$ $^{+30}_{-85}\%$

△=Blank space

5	
Nomin	al Capacitance
example	
010	1
1R2	1.2
103	10000
	<pre>%R=decir</pre>

	6	
e(pF)	Capaci	tance Tolerances
	D-	±0.5pF
	J-	± 5%
	K-	±10%
	M-	±20%
cimal point	Z-	$\pm^{80}_{20}\%$

A-

KF

KE

_ B-

Lead Configuration

bulk

bulk NA Axial lead, bulk

26mm lead space, ammo pack

52mm lead space, ammo pack

5.0mm pitch formed lead

7.5mm pitch formed lead

8 Packa	ging
В	Ammo
C	Bulk

9	
Interna	al code
$ \bigtriangleup $	Monolithic type
	Standard products
ΔZ	Multilayer type
	Standard products
$\triangle J$	Multilayer type
	(Low voltage products)
	∠=Blank space

TAIYO YUDEN 2008

外形寸法	EXTERNA	L DIMENS	SIONS	The second s		1				
TYPE		Dimensions		テーピング品 Taped product	単品 Bu	Bulk Product				
TTPE	L	φD	φd	ストレート Straight	ストレート Straight	フォーミング Formed				
単層形050 (Monolithic Type)	3.5max (0.138max)	1.9max (0.075max)	0.45±0.05 (0.018±0.002)	^B E		Pitch: (0.197)				
積層形075 (Multilayer Type)	4.2max (0.165max)	3.2max (0.126max)	0.55±0.05 (0.022±0.002)	i≺i 52mm (2.05)	N A	Pitch:7.5mm (0.295)				
積層形050 (Multilayer Type)	3.2max (0.126max)	2.2max (0.087max)	0.45 1.0.05			K F				
積層形025 (Multilayer Type)	2.3max (0.09max)	2.0max (0.079max)	0.45±0.05 (0.018±0.002)	26mm (1.02)		Pitch: (0.197)				
積層形015 (Multilayer Type)	3.0max (0.118max)	2.5max (0.098max)				(0.197)				

Unit : mm (inch)

ass 1	(Temperatu	re com	pensa	ting)				Class 2 (H	ligh dielecti	ic c	ons	stan	t)						積	層タ	17	プ (M	ultila	yer ty	pe)	
	WV I			50V (L	JP)			N	N I			50	, v (U	P)	35V	(GP)		25	V (TF)		16V	(EP)			101
Temp	o.char.	С	Н	RH	UJ	S	L	Temp	.char.		В			F	В	F		В		F		В		F		F
Туре	e cap.	025	050	050	050	025	050	Туре	cap.	005	050	075	015	025 050	075	075	015	075	0.05	050	015	005	050	015	150	
[pF]	[pF:3digits]	025	050	050	050	025	050	[pF]	[pF:3digits]	025	050	0/3	015	025 050	10/5	0/5	015	0/5	025	050	015	025	050	015	100	
1	010							75	750																	
1.2	1R2							82	820																	
1.5	1R5							91	910																_	Ŀ
1.8	1R8							100	101																	E
2.2	2R2							120	121																	
2.7	2R7 3R3							150	151 181																	E
3.3	3R3 3R9							180 220	221																_	h
3.9	3R9 4R7							220	271																	H
4.7 5.6	4R7 5R6							330	331																-	h
6.8	6R8							390	391																	Ľ
8.2	8R2							470	471																	h
0.2 10	100							560	561																	t
11	110							680	681																	h
12	120							820	821																	t
13	130							1000	102																	h
15	150							1200	122																	t
16	160							1500	152																	
18	180							1800	182																	Ľ
20	200							2200	222																	
22	220							2700	272																	Ľ
24	240							3300	332																	
27	270							3900	392											-						Г
30	300							4700	472																	t
33	330							5600	562																	Г
33 36	360	_						6800	682																	L
39	390							8200	822	_																Г
43	430							10000	103																	
47	470							15000	153																	Γ
51	510							22000	223																	
56	560							33000	333																	Γ
52	620							47000	473																	
68	680							68000	683																	
00	101							100000	104																	
50 20	151							220000	224																	
20	221							470000	474																	
30	331							1000000	105																	Γ
70	471							2200000	225																	
80	681							4700000	475																	
000	102							10000000	106																	l

※半層メイクの表面につきよしては、生産総定すよりで計構につきよしては取引の弁社営業志口よてお向い合わせ下さい。 ※Since the production of monolithic layer products is scheduled to be discontinued, please contact your nearest sales office if you require any detailed information.

温度特性 Temperature char.	静電容量変化率 Capacitance change	容量許容差 Capacitance Tolerance	Q又はtan δ Q or tan δ	種類 Class
CH	0± 60ppm/°C	D(±0.5pF) M(±20%)		1
RH	-220± 60ppm/°C	K (±10%)		
UJ SL	-750±120ppm/°C +350~-1000ppm/°C	J (±5%)		
3L	+350~-1000ppm/ C		アイテム一覧参照	
∆B	±10%	K (±10%)	eng • Refer to the Part munber	2
△F	±30 85%	Z (± ⁸⁰ %)		

※20℃における静電容量を基準。

*Capacitance characteristics measured at 20°C



[単層タイプ Monolithic type] — Class 1

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定格		E	EHS	·ㅁ 순 4+ 14	公 称	容量		
電圧	形名	(Envir	onmental	温度特性	静電容量	許 容 差		絶縁抵抗
RatedVoltage		Haz	zardous	Temperature	Capacitance	Capacitance	Q or tan δ	Insulation
(DC)	Ordering code		stances)	characteristics	(pF)	tolerance		resistance
(20)	UP050 010M-0		oHS		1.0	tororanoo		
	UP050 1R2M-0		oHS	СН	1.2	±20%		
	UP050 1R5M-0		RoHS RH 1.5					
			oHS	SL	1.8			
			oHS		2.2			
	UP050 \(\triangle 2R7K-\)		oHS		2.7			
	UP050_3R3K-O		oHS		3.3			
	UP050_3R9K-O		oHS		3.9			
	UP050 4R7K-0	R	oHS		4.7	±10%	Q≧400+20C	
	UP050_5R6K-O	R	oHS	СН	5.6		(C:公称静電容量	
	UP050_6R8K-O	R	oHS	RH	6.8		(0.五前前电子重 capacitance[pF])	
	UP050	R	oHS	UJ	8.2		ただしRHは	
	UP050△100J-〇	R	oHS	SL	10			
	UP050△110J-〇	R	oHS		11		16pF以上は	10000140
	UP050△120J-〇	R	oHS		12		Q≧500	
	UP050△130J-〇	R	oHS		13		but Q≧500	
50V	UP050△150J-〇	R	oHS		15		at 16pF or over	10000MΩmin
	UP050△160J-〇	R	oHS		16		of characteristic RH	
	UP050△180J-〇	R	oHS		18			
	UP050 \(\triangle 200 J-\)	R	oHS	CH、UJ、SL	20			
	UP050 \(\triangle 220 J-\)	R	oHS		22			
	UP050 \(\triangle 240 J-\)	R	oHS	UJ	24			
	UP050△270J-○		oHS	SL	27			
	UP050_300J-O		oHS		30			
	UP050SL330J-()		oHS		33	±5%		
	UP050SL360J-()		oHS		36		Q≧500	
	UP050SL390J-()		oHS		39			
	UP050SL430J-()		oHS		43			
	UP050SL470J-()		oHS	SL	47			
	UP050SL510J-O		oHS		51	_		
	UP050SL560J-O		oHS		56			
	UP050SL620J-O		oHS		62			
	UP050SL680J-()	R	oHS	IS	68			

形名の△には温度特性、○にはリード形状分類記号が入ります。

riangle Please specify the temperature characteristics code and riangle lead configuration code.

Class 1	Multilayer 025 Type]							
定格	形名		EHS	温度特性	公 称	容量		絶縁抵抗
電圧		(Er	nvironmental	Temperature	静電容量	許容差	Q or tan δ	Insulation
RatedVoltage	Ordering and		Hazardous	characteristics	Capacitance	Capacitance	QUITATIO	resistance
(DC)	Ordering code	s	Substances)	characteristics	(pF)	tolerance		resistance
	UP025△010D-〇 Z		RoHS		1.0			
	UP025△1R2D-〇 Z		RoHS		1.2			
	UP025△1R5D-O Z		RoHS		1.5			
	UP025△1R8D-O Z		RoHS 1.8					
	UP025 2R2D - CZ		RoHS		2.2	±0.5pF		
	UP025_2R7D-O Z		RoHS		2.7			1
	UP025_3R3D-O Z		RoHS 3.3					
	UP025_3R9D-O Z							
	UP025△4R7D−○ Z		RoHS		4.7		Q≧400+20C	10000MΩmin
	UP025△5R6K−○ Z		RoHS	_	5.6		Q=+00+200	
	UP025△6R8K−⊖ Z		RoHS	_	6.8	±10%		
	UP025△8R2K-〇 Z		RoHS	СН	8.2			
	UP025△100J-〇 Z		RoHS	SL	10			
	UP025△120J-〇 Z		RoHS		12			
	UP025△150J-〇 Z		RoHS	_	15			
50V	UP025△180J-〇 Z		RoHS	_	18			
	UP025_220J-0 Z		RoHS	_	22			
	UP025△270J-〇 Z		RoHS		27			
	UP025_330J-O Z		RoHS	_	33			
	UP025_390J-O Z		RoHS	_	39			
	UP025△470J−○ Z		RoHS	-	47			
	UP025△560J−○ Z		RoHS	_	56	±5%		
	UP025△680J−○ Z		RoHS	_	68			
	UP025_820J-0 Z		RoHS		82			
	UP025CH101J-O Z		RoHS	-	100		Q≧1000	
	UP025CH151J-O Z		RoHS	_	150			
	UP025CH221J-OZ		RoHS		220			
	UP025CH331J-O Z		RoHS	СН	330			
	UP025CH471J-O Z		RoHS		470			
	UP025CH681J-O Z		RoHS		680			
	UP025CH102J-O Z		RoHS		1000			

[積層025タイプ Multilayer 025 Type] -

形名の△には温度特性、○にはリード形状分類記号が入ります。

 $\bigtriangleup Please$ specify the temperature characteristics code and \bigcirc lead configuration code.

[積層015タイプ Multilayer 015type] -Class 2

定格 電圧 RatedVoltage (DC)	形 名 Odering Code	EHS (Environmental Hazardous Substances)	温度特性 Temperature characteristics	公称 静電容量 Capacitance [pF]	容量 許容差 Capacitance tolerance	Q or tanδ	絶縁抵抗 Insulation resistance
25V	TP015 B103K-O Z	RoHS	D	10000	±10%	tanδ≦3.5%	$5000M\Omega$ min
16V	EP015 B104K-O Z	RoHS	В	100000	±10%	tanδ≦5.0%	1000MΩmin
50V	UP015 F103Z-O Z	RoHS	E	10000	+80 %	tanδ≦7.5%	1000MQmin
16V	EP015 F104Z-O Z	RoHS	г	100000	-20 %	tanδ≦10.0%	1000101211111

形名の△には温度特性、○にはリード形状分類記号が入ります。

rianglePlease specify the temperature characteristics code and riangle lead configuration code.

Class 2								
定格	形名		EHS	温度特性	公 称	容量		絶縁抵抗
電圧	/1/2 12		(Environmental		静電容量	許容差	O an tan 5	
RatedVoltage			Hazardous	Temperature	Capacitance	Capacitance	Q or tan δ	Insulation
(DC)	Ordering code		Substances)	characteristics	(pF)	tolerance		resistance
(20)	UP025 B101K - C Z		RoHS		100			
	UP025 B121K - O Z		RoHS		120			
	UP025 B151K - C Z		RoHS		150			
	UP025 B181K - C Z		RoHS		180			
	UP025 B221K - C Z		RoHS		220			
	UP025 B271K - O Z				270			
	UP025 B331K - O Z				330			
	UP025 B391K - O Z		RoHS		390			
	UP025 B471K - O Z		RoHS		470			
	UP025 B561K - O Z		RoHS		560			
	UP025 B681K - Z		RoHS		680			
	UP025 B821K - C Z		RoHS		820		tanδ≦3.5%	5000MΩmin
	-		RoHS				tan 0 = 3.5%	30001012211111
50V	UP025 B102K - Z		RoHS	В	1000	±10%		
	UP025 B122K - Z		RoHS					
	UP025 B152K - Z		RoHS		1500			
	UP025 B222K - Z		RoHS		2200			
	UP025 B332K - Z		RoHS		3300			
	UP025 B472K - Z		RoHS	_	4700			
	UP025 B682K - Z		RoHS		6800			
	UP025 B103K - Z		RoHS		10000			
	UP025 B153K - C Z		RoHS		15000			
	UP025 B223K - C Z		RoHS		22000			
	UP025 B333K - C Z		RoHS		33000			
	UP025 B473K - OZ		RoHS		47000		$\tan \delta \leq 5.0\%$	
	UP025 B683K - C Z		RoHS		68000			1000MΩmii
	UP025 B104K - C Z		RoHS		100000			
	UP025 F103Z - C Z		RoHS		10000			
50V	UP025 F223Z - OZ		RoHS	F	22000	+80 _% -20 [%]	tanδ≦7.5%	1000MΩmin
	UP025 F473Z - C Z		RoHS		47000		tan0 ≧7.5%	
	UP025 F104Z - C Z		RoHS		100000			
	EP025 B122M - O J		RoHS		1200			
	EP025 B152M - O J		RoHS		1500			
	EP025 B182M - O J		RoHS		1800			
	EP025 B222M - O J		RoHS		2200			
	EP025 B272M - O J		RoHS		2700			
	EP025 B332M - O J		RoHS		3300			
	EP025 B392M - O J		RoHS		3900			
16V	EP025 B472M - O J		RoHS	в	4700	±20%	tanδ≦3.5%	5000M Ω mir
100	EP025 B562M - O J		RoHS		5600	-2070	tan 0 = 0.070	50001013211111
	EP025 B682M - 🔾 J		RoHS		6800			
	EP025 B822M - O J		RoHS		8200			
	EP025 B103M - O J		RoHS		10000			
	EP025 B123M - O J		RoHS		12000			
	EP025 B153M - O J		RoHS		15000			
	EP025 B183M - O J		RoHS		18000			
	EP025 B223M - O J		RoHS		22000			
	TP025 F103Z - O J		RoHS		10000			
25V	TP025 F223Z - O J		RoHS	F	22000	+80 _% -20 [%]	$\tan \delta \leq 7.5\%$	1000M Ω min
257								

形名の△には温度特性、○にはリード形状分類記号が入ります。

 $\bigtriangleup Please$ specify the temperature characteristics code and \bigcirc lead configuration code.

[積層タイプ Multilayer type] -

Class 1	5 51 -						
定格	形名	EHS	温度特性	公称	容量		絶縁抵抗
電圧	112 12	(Environmer	tal Temperature	静電容量	許容差	Q or tan δ	Insulation
RatedVoltage) Oudering and	Hazardou	characteristics	Capacitance	Capacitance	Qortano	resistance
(DC)	Ordering code	Substance	s)	(pF)	tolerance		resistance
	UP050CH220J-OZ	RoHS		22			
*	UP050CH240J-OZ	RoHS		24		Q≧400+20C	
	UP050CH270J-OZ	RoHS		27		Q=4001200	
*	UP050CH300J-OZ	RoHS		30			
	UP050CH330J-OZ	RoHS		33			
*	UP050CH360J-OZ	RoHS		36			
	UP050CH390J-O Z	RoHS		39			
*	UP050CH430J-O Z	RoHS		43			
	UP050CH470J-O Z	RoHS		47			
*	UP050CH510J-O Z	RoHS		51			
	UP050CH560J-OZ	RoHS		56			
*	UP050CH620J-OZ	RoHS		62	_		
	UP050CH680J-O Z	RoHS		68	_		
*	UP050CH750J-O Z	RoHS		75	_		
*	UP050CH820J-OZ	RoHS		82	_		
*	UP050CH910J-OZ	RoHS		91	_		
	UP050CH101J-OZ	RoHS		100	_		
*	UP050CH111J- O Z	RoHS		110	_		
*	UP050CH121J- O Z	RoHS		120			
*	UP050CH131J- O Z	RoHS		130	_		
50V	UP050CH151J- O Z	RoHS	СН	150	± 5%	Q≧1000	10000MΩmin
*	UP050CH161J- O Z	RoHS		160	_		
*	UP050CH181J- O Z	RoHS		180	_		
*	UP050CH201J-O Z	RoHS		200	_		
	UP050CH221J-OZ	RoHS		220	_		
*	UP050CH241J-OZ	RoHS		240	_		
*	UP050CH271J-OZ	RoHS		270	_		
*	UP050CH301J- O Z	RoHS		300	_		
	UP050CH331J- O Z	RoHS		330	_		
*	UP050CH361J- O Z	RoHS		360	_		
*		RoHS		390	_		
*	UP050CH431J- O Z	RoHS		430	_		
-	UP050CH471J- O Z	RoHS		470	_		
*	UP050CH511J- O Z	RoHS		510	_		
*		RoHS	_	560	-		
*		RoHS	_	620	-		
-	UP050CH681J- O Z UP050CH751J- O Z	RoHS RoHS	_	680 750	-		
*	UP050CH751J-0 Z		_		-		
*	UP050CH911J- O Z	RoHS	_	820	-		
*		RoHS	_	910	-		
	UP050CH102J-0 Z	RoHS		1000			

形名の△には温度特性、○にはリード形状分類記号が入ります。 ★:オプション対応

riangle Please specify the temperature characteristics code and riangle lead configuration code.

★ : Option

[単層タイプ Monolithic type] — Class 2

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定格 電圧 RatedVoltage (DC)	形 名 Ordering code	EHS (Environmental Hazardous Substances)	温度特性 Temperature characteristics	公称 静電容量 Capacitance 〔pF〕	容量 許容差 Capacitance tolerance	Q or tan δ	絶縁抵抗 Insulation resistance
	UP050 B750K- ()	RoHS		75	_		
	UP050 B820K-O	RoHS		82			
	UP050 B910K-O	RoHS		91			
	UP050 B101K-O	RoHS		100			
	UP050 B121K-O	RoHS		120			
	UP050 B151K-()	RoHS	-	150	 	tan δ ≦1.5%	$10000M\Omegamin$
	UP050 B181K- 🔿	RoHS		180			
50V	UP050 B221K-O	RoHS	В	220			
500	UP050 B271K-O	RoHS	Б	270	1070		
	UP050 B331K- 🔿	RoHS		330	1		
	UP050 B391K-〇	RoHS		390]		
	UP050 B471K-O	RoHS		470	1		
	UP050 B561K- 🔿	RoHS		560	1		
	UP050 B681K- 🔿	RoHS		680	1	tanδ≦2.5%	
	UP050 B821K-O	RoHS		820	1		
	UP050 B102K-O	RoHS		1000	1		1000MΩmin
051/	TP050 F103Z-〇	RoHS	F	10000			
25V	TP050 F223Z-〇	RoHS	F	22000	$\pm \frac{80}{20}\%$	tanδ≦7.5%	

形名の〇には容量許容差、〇にはリード形状分類記号が入ります。

 $\hfill \mathsf{P}\mathsf{lease}$ specify the capacitance tolerance code and \bigcirc lead configuration code.

[積層タイプ Multilayer type] -

Class 2	wutilayer type]							
定格	T/ 47		EHS	温度特性	公 称	容量		絶縁抵抗
電圧	形名		(Environmental	Temperature	静電容量	許容差	O antan S	Insulation
RatedVolta			Hazardous		Capacitance	Capacitance	Q or tan δ	
(DC)	Ordering code		Substances)	characteristics	(pF)	tolerance		resistance
7	★ UP050 B122K-○ Z	7	RoHS		1200			
	UP050 B152K-O Z	7	RoHS		1500	-		
,	★ UP050 B182K-○ Z	2	RoHS		1800	-		
	UP050 B222K-O Z		RoHS		2200	-		
,	★ UP050 B272K-○ Z		RoHS		2700	-		
	UP050 B332K-O Z		RoHS		3300			
7	★ UP050 B392K-○ Z	2	RoHS		3900	-		
	UP050 B472K-O Z		RoHS		4700	-		
,	★ UP050 B562K-○ Z		RoHS		5600	-		
	UP050 B682K-O Z		RoHS		6800	-	tanδ≦3.5%	5000MΩmin
,	★ UP050 B822K-○ Z		RoHS		8200	-		
50V	UP050 B103K-O Z		RoHS		10000	-		
,	★ UP050 B123K-○ Z		RoHS		12000	-		
	UP050 B153K-O Z		RoHS		15000	-		
7	★ UP050 B183K-○ Z		RoHS	В	18000	±10%		
	UP050 B223K-O Z		RoHS		22000	-		
7	★ UP050 B273K-○ Z		RoHS		27000	-		
	UP050 B333K-O Z		RoHS		33000	-		
7	★ UP050 B393K-○ Z		RoHS		39000	-		
	UP050 B473K-O Z		RoHS		47000	-		
7	★ UP050 B563K-○ Z		RoHS		56000	-		
	UP050 B683K-O Z		RoHS		68000	-	$\tan \delta \leq 5.0\%$	1000M Ω min
7	✔ UP050 B823K-○ Z		RoHS		82000	-		
	UP050 B104K-O Z		RoHS		100000	-		
	UP050 B224K-O Z		RoHS		220000		500MΩmin	
	UP050 B474K-O Z		RoHS		470000	-		200MΩmin
	EP050 B105K-O Z		RoHS		1000000	-		100MΩmin
16V	EP050 B225K-O Z		RoHS		2200000	-		50MΩmin
	EP050 B475K-O Z		RoHS		4700000	-	$\tan \delta \leq 7.5\%$	
	EP050 B106K-O Z		RoHS		1000000	-	$\tan \delta \leq 12.5\%$	20MΩmin
	UP050 F103Z-0 Z		RoHS		10000			
	UP050 F223Z-O Z		RoHS		22000	1	$\tan \delta \leq 7.50/$	1000MΩmin
	UP050 F473Z-O Z		RoHS		47000	1	tanδ≦7.5%	
50V	UP050 F104Z-O Z		RoHS		100000			
	UP050 F224Z-O Z		RoHS	F	220000		tanδ≦10.0%	500MΩmin
	UP050 F474Z-0 Z		RoHS		470000	+80 %	tano = 10.070	50010122111111
	UP050 F105Z-0 Z		RoHS		1000000			250MΩmin
16V	EP050 F225Z-O Z		RoHS		2200000		$\tan \delta \leq 15\%$	125MΩmin
	LP050 F475Z-0 Z		RoHS		4700000			50MΩmin
10V	LP050 F106Z-O Z		RoHS		1000000	1	$\tan \delta \leq 17.5\%$	25MΩmin
50V	UP075 B105K-O		RoHS		1000000		tanδ≦5.0%	100MΩmin
	GP075 B225K-O		RoHS		2200000	1		50MΩmin
35V	GP075 B475K-O		RoHS	В	4700000	±10%	$\tan \delta \leq 7.5\%$	
25V	TP075 B106K-O		RoHS		1000000	-	$\tan \delta \leq 12.5\%$	20MΩmin
35V	GP075 F106Z-O		RoHS	F	1000000	+80 %	$\tan \delta \leq 17.5\%$	25MΩmin
-			-			-20		· · ·

形名の△には温度特性、○にはリード形状分類記号が入ります。 ★:オプション対応

 $\bigtriangleup {\sf P}{\sf lease}$ specify the temperature characteristics code and \bigcirc lead configuration code.

★ : Option



・静電容量-温度特性 Capacitance -vs- Temperature Characteristics





形式 Type	リード形状記号 Lead configuration	最小受注単位数(PCS) Minimum Quantity		
туре	code	袋づめ Bulk	テーピング Taping	
	A-(26mm幅) 1.024 inch wide		2000 (075type) 3000 (050type) 5000 (015,025type)	
積層形 Multilayer type	B-(52mm幅)2.047 inches wide		2000(075type) 3000(050type) 5000(015,025type)	
(075, 050, 025,015)	NA	1000		
	KE (075type) KF (015,025,050type)	3000, 4000 (015,025 type)		
	A-(26mm幅)1.024 inch wide		4000	
単層形 Monolithic type	B-(52mm幅)2.047 inches wide		4000	
(050)	NA	1000		
(200)	KF	3000		

①最小受注単位数 Minimum Quantity

②製品単品形状 Dimensions of Bulk Products

・NA形状 NA configuration



形式		寸 法 Din	nensions (mm)	
Туре	φD	L	φd	l
積層形 015	2.5max	3.0max	0.45±0.05	20.0min
Multilayer type	(0.098)	(0.118)	(0.018±0.002)	(0.787)
積層形 025	2.0max	2.3max	0.45±0.05	20.0min
Multilayer type	(0.079)	(0.09)	(0.018±0.002)	(0.787)
積層形 050	2.2max	3.2max	0.45±0.05	20.0min
Multilayer type	(0.087)	(0.126)	(0.018±0.002)	(0.787)
積層形 075	3.2max	4.2max	0.55±0.05	20.0min
Multilayer type	(0.126)	(0.165)	(0.022±0.002)	(0.787)
単層形050	1.9max	3.5max	0.45±0.05	20.0min
Monolithic type	(0.075)	(0.138)	(0.018±0.002)	(0.787)

Unit : mm (inch)

・KF/KE形状 KF/KE configuration



形 式 Type	リード形状記号 Lead configuration		寸 法	Dimensi	ions(mm)	
Type	code	φD	L	W	φd	l
積層形 015	KF	2.5max	3.0max	5.0±0.5	0.45±0.05	6.5±0.5
Multilayer type	КГ	(0.098max)	(0.118max)	(0.197±0.020)	(0.018±0.002)	(0.256±0.020)
積層形 025	KF	2.0max	2.3max	5.0±0.5	0.45±0.05	6.5±0.5
Multilayer type	Γ\Γ	(0.079max)	(0.09max)	(0.197±0.020)	(0.018±0.002)	(0.256±0.020)
積層形 050	KF	2.2max	3.2max	5.0±0.5	0.45±0.05	6.5±0.5
Multilayer type	NF	(0.087max)	(0.126max)	(0.197±0.020)	(0.018±0.002)	(0.256±0.020)
積層形 075	KE	3.2max	4.2max	7.5±0.5	0.55±0.05	6.5±0.5
Multilayer type	NE	(0.126max)	(0.165max)	(0.295±0.020)	(0.022±0.002)	(0.256±0.020)
単層形050	KF	1.9max	3.5max	5.0±0.5	0.45±0.05	6.5±0.5
Monolithic type		(0.075max)	(0.138max)	(0.197±0.020)	(0.018±0.002)	(0.256±0.020)
					L Init ' i	mm(inch)

 $\mathsf{Unit}:\mathsf{mm}(\mathsf{inch})$

③テーピング寸法 Taping Dimensions

A- (a:26mm幅)形状 (a:1.024 inch wide) configuration



×	
	-
	- 3
	- 2

形 式 Type		4	法	Dimensi	ons		最小挿入 ピッチ Minimum
турс	φD	L	а	b	$ L_1 - L_2 $	φd	insertion pitch
積層形 015	2.5max	3.0max				0.45±0.05	
Multilayer type	(0.098max)	(0.118max)				(0.018±0.002)	
積層形 025	2.0max	2.3max				0.45±0.05	5.0
Multilayer type	(0.079max)	(0.09max)	$26^{+0.5}_{-0}$			(0.018±0.002)	(0.197)
積層形 050	2.2max	3.2max		0.8以下	0.5max	0.45±0.05	
Multilayer type	(0.087max)	(0.126max)	(1.024 ^{+0.020} -0)	(0.031 or less)	(0.020max.)	(0.018±0.002)	
積層形 075	3.2max	4.2max]			0.55±0.05	7.5
Multilayer type	(0.126max)	(0.165max)				(0.022±0.002)	(0.295)
単層形050	1.9max	3.5max				0.45±0.05	5.0
Monolithic type	(0.075max)	(0.138max)				(0.018±0.002)	(0.197)
							(1 1)

Unit:mm(inch)





形 式 Type		4	法	Dimensi	ons		最小挿入 ピッチ Minimum
iypo	φD	L	а	b	$ L_1 - L_2 $	φd	insertion pitch
積層形 015	2.5max	3.0max				0.45±0.05	
Multilayer type	(0.098max)	(0.118max)				(0.018±0.002)	
積層形 025	2.0max	2.3max				0.45±0.05	5.0
Multilayer type	(0.079max)	(0.09max)	52^{+2}_{-1}			(0.018±0.002)	(0.197)
積層形 050	2.2max	3.2max		1.2以下	1.0max	0.45±0.05	
Multilayer type	(0.087max)	(0.126max)	(2.047 ^{+0.079} _{-0.039})	(0.047 or less)	(0.039max.)	(0.018±0.002)	
積層形 075	3.2max	4.2max				0.55±0.05	7.5
Multilayer type	(0.126max)	(0.165max)				(0.022±0.002)	(0.295)
単層形050	1.9max	3.5max				0.45±0.05	5.0
Monolithic type	(0.075max)	(0.138max)				(0.018±0.002)	(0.197)
						Unit : m	m(inch)

※075Typeはラジアルテーピングもオプション対応可能。

TAIYO YUDEN 2008

State Street Street

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AXIAL LEADED CERAMIC CAPACITORS

Multilayer type Multilayer type (Characteristics:B) Multilayer type (Characteristics:F) 1. Operating Temperature Range -25~+85°C 2. Storage Temperature Range -25~+85°C 3. Rated Voltage 50VDC 4. Withstanding Voltage Between terminals and body No abnorminality 16VDC. 25VDC. 35VDC. 50VDC 10VDC. 16VDC. 25VDC. 35VDC. 50VDC 5. Insulation Resistance No abnorminality Rated Ivoltage:16VDC B: 1000000pF Rated Ivoltage:16VDC B: 1000000pF Rated Ivoltage:10VDC F: 1000000pF Rated Ivoltage:10VDC F: 1000000pF Applied voltage: Rated Voltage (Class 2) Duration: 1 to 5 sec. 5. Insulation Resistance 10000MΩmin. Rated Ivoltage:16VDC B: 1000000pF Rated Ivoltage:10VDC F: 1000000pF Rated Ivoltage:16VDC F: 1000000pF Applied voltage: Rated voltage Uration: 1 to 5 sec. 5. Insulation Resistance 10000MΩmin. Rated Ivoltage:10VDC B: 100000pF Rated Ivoltage:16VDC F: 100000pF F: 100000pF Applied voltage: Rated voltage 2200000pF Applied voltage: Rated voltage 2200000pF 8 Rated Ivoltage:25VDC B: 100000pF Rated voltage:35VDC R: Rated voltage:35VDC F: 100000pF	
Range -25~+85°C Storage Temperature Range -25~+85°C I Rated Voltage 50VDC 1 Rated Voltage 50VDC Withstanding Voltage Between terminals No abnorminality Between terminals No abnorminality Image 0 No abnorminality Metal globule method Applied voltage: Rated Voltage (Class 2) Duration: 1 to 5 sec. Charge/discharge current: 50 100000pF 100000pF 100000pF 100000pF 100000pF 100000pF 1000000pF 1000000pF 1000000pF 100000	
Storage Temperature Range -25~+85°C Rated Voltage 50VDC Insulation light 50VDC Between terminals and body No abnorminality Insulation Resistance 10000MΩmin. Rated Voltage: 10000MΩmin. Rated Voltage: 100000F 100000F :10000ΩF 100000F :200000F 100000F :200000F 1000000F :200000F 1000000F :200000F 1000000F :200000F 1000000F :200000F 1000000F :200000F 1000000F :200000F Rated Ivoltage:25VDC Bated Ivoltage:35VDC Bated Ivoltage:35VDC	
Rated Voltage 50VDC 16VDC, 25VDC, 35VDC, 50VDC 10VDC, 16VDC, 25VDC, 35VDC, 50VDC Applied voltage: Rated Voltage (Class 1) Rated Voltage Withstanding Voltage Between terminals No abnorminality No abnorminality Applied voltage: Rated Voltage (Class 2) Duration: 1 to 5 sec. Charge/discharge current: 500 Between terminals and body No abnorminality Metal globule method Applied voltage: Rated Voltage (Class 2) Metal globule method Applied voltage: Rated Voltage Duration: 1 to 5 sec. Charge/Discharge current: 50 Insulation Resistance 10000MΩmin. Rated lvoltage:16VDC B: 100000pF Rated lvoltage:10VDC F: 100000pF Rated lvoltage:10VDC F: 100000pF Applied voltage: Rated voltage Duration: 60±5 sec. Insulation Resistance 100000pF :1000MΩmin 100000pF Rated lvoltage:10VDC F: 100000pF Rated lvoltage:10VDC F: 100000pF Applied voltage: Rated voltage Duration: 60±5 sec. Insulation Resistance 100000pF :200000pF :200MΩ min 100000pF Rated lvoltage:10VDC F: 100000pF Applied voltage: Rated voltage Duration: 60±5 sec. Insulation Resistance Rated lvoltage:25VDC B: 100000pF F: 10000PF Rated lvoltage:25VDC F: 10000PF F: 10000PF Picture Applied voltage Insulation Resistance Rated lvoltage:25VDC B: 100000pF	
Withstanding Voltage Between terminals No abnorminality Applied voltage: Rated Voltage (Class 1) Rated Voltage (Class 2) Between terminals and body No abnorminality Motabnorminality Metal globule method Applied voltage: Rated Voltage (Class 2) Insulation Resistance 10000MΩmin. Rated Ivoltage:16VDC B: 100000pF Rated Ivoltage:10VDC B: 100000pF Rated Ivoltage:10VDC B: 100000pF Rated Ivoltage:10VDC B: 100000pF Applied voltage: Rated voltage Duration: 1 to 5 sec. Charge/Discharge current: 50 Insulation Resistance 10000MΩmin. Rated Ivoltage:16VDC B: 100000pF Rated Ivoltage:10VDC B: 100000pF Rated Ivoltage:10VDC F: 100000pF Applied voltage: Rated voltage Duration: 1 to 5 sec. Charge/Discharge current: 50 Insulation Resistance 100000MΩmin. Rated Ivoltage:16VDC B: 100000pF Rated Ivoltage:10VDC F: 100000pF Applied voltage: Rated voltage Duration: 60±5 sec. Insulation Resistance 100000pF :50MΩ min 100000pF Rated Ivoltage:10VDC F: 100000pF Applied voltage: Rated voltage Duration: 60±5 sec.	
terminals and body Applied voltage: Rated Voltage Duration: 1 to 5 sec. Charge/Discharge current : 50 Insulation Resistance 10000MΩmin. Rated Ivoltage:16VDC B: 100000pF :1000MΩmin 1000000pF :100MΩmin 2200000pF :50MΩ min 4700000pF :20MΩ min 12000pF~20000pF(Item:△J):500MΩmin 12000pF~20000pF(Item:△J):500MΩmin 12000pF :5000MΩmin 100000pF :1000MΩmin Rated Ivoltage:25VDC B: 10000pF :5000MΩmin Rated Ivoltage:25VDC B: 10000pF :5000MΩmin Rated Ivoltage:25VDC B: 10000pF :20MΩ min Rated Ivoltage:25VDC B: 10000pF :20MΩ min Rated Ivoltage:25VDC B: 10000pF :20MΩ min Rated Ivoltage:25VDC Applied voltage: Rated Voltage Duration : 60±5 sec.	
B: F: Duration: 60±5 sec. 100000pF :1000MΩmin 4700000pF :50MΩ min 1000000pF :000MΩmin 4700000pF :25MΩ min 2200000pF :50MΩ min Rated Ivoltage:16VDC F: 100000pF :1000MΩmin Rated Ivoltage:16VDC F: 10000pF :20000pF(Item:△J):500MΩmin Rated Ivoltage:25VDC 2200000pF :1000MΩmin B: 10000pF :5000MΩmin Rated voltage:25VDC F: 100000pF :1000MΩmin B: 10000pF :5000MΩmin Rated voltage:25VDC F: 10000pF :20MΩ min B: 10000pF :20MΩ min Rated voltage:25VDC F: 10000pF :20MΩ min 10000pF :20MΩ min Rated voltage:35VDC F: 10000MΩmin F: 10000pF :20MΩ min Rated voltage:35VDC D: D: :1000MΩmin	
100000pF :1000MΩmin 4700000pF :50MΩ min 100000pF :50MΩ min 1000000pF :25MΩ min 2200000pF :50MΩ min 1000000pF :25MΩ min 4700000pF~200000pF :20MΩ min Rated Ivoltage:16VDC F: 1200pF~22000pf(Item:△J):500MΩmin 100000pF :1000MΩmin 2200000pF Rated Ivoltage:25VDC 2200000pF :1000MΩmin F: 10000pF :500MΩmin Rated voltage:25VDC F: B: :5000MΩmin Rated voltage:25VDC F: 100000pF :20MΩ min F: 10000pF 100000pF :20MΩ min Rated voltage:25VDC F: B: :20MΩ min F: 10000pF :1000MΩmin Rated Ivoltage:35VDC F: 10000pF :1000MΩmin Rated Ivoltage:35VDC F: 10000pF :1000MΩmin	•
2200000pF :50MΩ min F: 4700000pF :20MΩ min 10000000pF Rated Ivoltage:50VDC B: 1000pF~39000pF 1000pF~39000pF :5000MΩ min 100000pF~100000pF 47000pF~100000pF :10000pF~100000pF :500MΩ min 220000pF :5000MΩ min 100000pF~100000pF :500MΩ min 47000pF :500MΩ min 100000pF :500MΩ min 470000pF :20000pF :20000pF :250MΩ min	
100000pF :100MΩ min . Capacitance : ±0.5pF Rated Ivoltage:16VDC Rated Ivoltage:10VDC Measuring frequency	
$ \begin{array}{c} \pm 5\% \\ \pm 10\% \end{array} \begin{array}{c} B: \pm 10\%, \pm 20\% (\text{Item} \triangle J) \\ \pm 10\% \end{array} \begin{array}{c} F: \pm 80 \\ -20\% \end{array} \begin{array}{c} 1 \\ \text{MHz} \pm 10\% (\text{Class 1: } C \le 100 \\ 1 \\ \text{KHz} \pm 10\% (\text{Class 2}) \\ \text{Kated lvoltage: 25VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 25VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 25VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 25VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 25VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 25VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 25VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 25VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 25VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 25VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 55VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 35VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 35VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 55VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 55VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 55VDC} \\ B: \pm 10\% \end{array} \begin{array}{c} \text{Rated lvoltage: 55VDC} \\ F: \pm 80 \\ -20\% \end{array} \end{array} \begin{array}{c} \text{Rated lvoltage: 55VDC} \\ Bis a application: None \end{array} \end{array}$	00pF)
. Q or Tangent of Loss Angle 30pF or under : Rated Ivoltage:16VDC Rated Ivoltage:10VDC	
Image: Constraint of Carbon of Car	
1000000pF :15.0% max	
	erature characterist ; 1) (ppm/°C)
Bated Ivoltage:50VDC Temperature at step 3: 20°C (Re F: +30 -85%	ture at step 4: 85°C operature at step 5: 20

Withstanding voltage is also referred to as "voltage proof" under IEC specifications.

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AXIAL LEADED CERAMIC CAPACITORS

Ite	m	Temterature Compensating(Class1)	Specified Va	High Permitt	ivity(Class2) Multilayer type(Charact	eristics (F)	Test	Methods and	Remarks
Terminal	Tensile	Multilayer type No abnomalities, such as cuts or		icienstics:B)	waimayer type(Charact	ensucs:F)	Apply the stated	tensile force	progres-
Strength		,					sively in the dire		
								1	
							Nominal wire diameter	Tensile force	
							[mm] 0.45	[N] 19.6	[s] 5
								1010	
-	Torsional	No abnomalities, such as cuts or	looseness of terminals.				Suspend a mass a through angle of 90		erminal, incline the b o initial position.
								e opposite dire	period of 5 sec. T ection shall be mad
								Bending force	Mass weight
							[mm]	[N]	[kg]
							0.45	2.45	0.25
Resistance	e to Vaibration	Appearance : No significant abnomalit			Appearance : No significant		According to JIS	C 5102 claus	e 8.2
		Withstanding Voltage : No abnomality Capacitance :	Withstanding Voltage : N		Withstanding Voltage : No a		Vibration type: A		
		Within ±5%	Rated Voltage:16VDC		Rated Voltage:10VDC		Directions: 2 hrs	each in X, Y a	nd Z directions
		4.7pF or under :Within ± 0.5 p 5.6pF \sim 8.2pF :Within $\pm 10\%$	F B Capacitance	: Within ±10%	F Capacitance : Within+8	0 ~	Total: 6 hrs	, -	
		10pF or over :Within ±5%	1200pF~22000pF(Item△J)	:Within $\pm 20\%$	Capacitance : Within $\frac{+8}{-2}$	0 %	Frequency range	: 10 to 55 to 1	0Hz (1min)
		Q: 30pF or under :	100000pF~10000000pF tanδ:	:Within ±10%	tanδ: 4700000pF~1000000pF:	17.5% max	Amplitude: 1.5 m		
		Q≧400+20C 33pF or over :	1200pF~22000pF(Item△J) 100000pF	:3.5%max :5.0%max	Insulation Resistance: 4700000pF	:50MΩ min	Mounting metho	d: Soldering o	nto the PC board
		Q≧1000	1000000pF	:5.0% max	10000000pF	:25MΩ min			
		Insulation resistance : 10000MΩ min.	2200000pF~4700000pF 10000000pF	:7.5% max :12.5% max	Rated Voltage:16VDC				
			Insulation Resistance: 1200pF~22000pF(Item△J)	:5000MΩmin	F				
		C:Nominal Capacitance :[pF]	100000pF	:1000MΩmin	Capacitance : Within +80 -20 %				
			1000000pF 2200000pF	:100MΩmin :50MΩmin	tanδ: 100000pF	:10.0%max			
			4700000pF~1000000pF	:20MΩmin	2200000pF	:15.0% max			
			Rated Voltage:25VDC		Insulation Resistance: 100000pF	1000MΩmin			
			В	·Within ±100/		:125MΩmin			
			Capacitance tanδ:	: Within $\pm 10\%$	Rated Voltage:25VDC				
			10000pF 1000000pF Insulation Resistance:	:3.5%max :12.5%max	F Capacitance : Within+80 -20 %				
			10000pF 1000000pF	:5000MΩmin :20MΩmin	tanδ: 10000pF~47000pF(Item△J) Insulation Resistance:	:7.5%max			
			Rated Voltage:35VDC B		10000pF~47000pF(Item△J)	:1000MΩmin			
			Capacitance tanδ:	: Within $\pm 10\%$	Rated Voltage:35VDC F				
			2200000pF~4700000pF Insulation Resistance: 2200000pF	:7.5%max :50MΩmin	tan δ :				
			4700000pF Rated Voltage:50VDC	:20MΩmin	10000000pF Insulation Resistance: 10000000pF	:17.5%max :25MΩmin			
			В	: Within ±10%	Rated Voltage:50VDC				
			tanδ:		F				
			100pF~39000pF 47000pF~1000000pF	:3.5% max :5.0% max	Capacitance : Within+80 %				
			Insulation Resistance: 100pF~39000pF		tanδ: 10000pF~100000pF	:7.5%max			
			47000pF~100000pF	:5000MΩ min :1000MΩ min	220000pF~470000pF	:10.0%max			
			220000pF 470000pF	:500MΩ min :200MΩ min	1000000pF Insulation Resistance:	:15.0%max			
			1000000pF	:100MΩ min		000MΩmin :500MΩmin			
					1000000pF	:250MΩmin			
		1	1		1				

Withstanding voltage is also referred to as "voltage proof" under IEC specifications.

AXIAL LEADED CERAMIC CAPACITORS

Item	Temterature Compensating(Class1)	Specified Value High Permit	tivity(Class2)	Test Methods and Remarks
	Multilayer type	Multilayer type (Characteristics:B)	Multilayer type(Characteristics:F)	
. Free Fall	Appearance : No significant abnomality	Appearance : No significant abnomality		Drop Test: Free fall
	Withstanding Voltage : No abnomality Capacitance :	Withstanding Voltage : No abnomality	Withstanding Voltage : No abnomality	Impact material: Floor
	4.7pF or under :Within ±0.5pF	Rated Voltage:16VDC	Rated Voltage:10VDC	Height: 1 m
	5.6pF~8.2pF :Within ±10%	В	F	Total number of drops: 5 times
	10pF or over :Within ±5%	Capacitance :	Capacitance : Within+80 %	Total number of drops. 5 times
	Q:	1200pF~22000pF(Item△J):Within±20% 100000pF~1000000pF :Within±10%	tanδ:	
	30pF or under :	tanδ:	4700000pF~1000000pF: 17.5% max	
	Q≧400+20C	1200pF~22000pF(Item△J) :3.5% max	Insulation Resistance:	
	33pF or over :	100000pF :5.0%max	4700000pF :50MΩ min 1000000pF :25MΩ min	
	Q≧1000 Insulation resistance :	1000000pF :5.0% max 2200000pF~4700000pF :7.5% max		
	10000MΩ min.	10000000pF :12.5% max		
		Insulation Resistance:	F	
	C:Nominal Capacitance :[pF]	1200pF~22000pF(Item△J) :5000MΩ min 100000pF :1000MΩ min		
		100000pF :1000MΩ min 1000000pF :100MΩ min		
		2200000pF : 50MΩ min	tanδ:	
		4700000pF~1000000pF :20MΩ min	100000pF :10.0% max	
			2200000pF :15.0% max Insulation Resistance:	
		Rated Voltage:25VDC B	100000pF :1000MΩ min	
		Capacitance : Within ±10%		
		tanδ:		
		10000pF :3.5%max	Rated Voltage:25VDC	
		1000000pF :12.5%max	F Capacitance : Within ±80 or	
		Insulation Resistance: 10000pF :5000MΩ min	Capacitance : Within +80 -20 %	
		1000000pF .5000MΩ min 1000000pF :20MΩ min	tanδ:	
			10000pF~47000pF(Item△J) :7.5%max	
		Rated Voltage:35VDC	Insulation Resistance: 10000pF~47000pF(Item△J) :1000MΩ min	
		B Capacitance : Within ±10%		
		tanδ:	Rated Voltage:35VDC	
		2200000pF~4700000pF :7.5%max	F	
		Insulation Resistance:	Capacitance : Within+80 %	
		2200000pF :50MΩ min 4700000pF :20MΩ min		
		20M2 min	1000000pF :17.5% max	
		Rated Voltage:50VDC	Insulation Resistance:	
		В	1000000pF :25MΩ min	
		Capacitance : Within ±10%	Rated Voltage:50VDC	
		tanδ: 100pF~39000pF :3.5%max	F	
		47000pF~100000pF :5.0%max	Capacitance : Within+80 %	
		Insulation Resistance:	-20 / 1	
		100pF~39000pF :5000MΩ min		
		47000pF~100000pF :1000MΩ min	10000pF~100000pF :7.5% max	
		220000pF :500MΩ min 470000pF :200MΩ min	220000pF~470000pF :10.0% max	
		100000pF :100MΩ min	1000000pr .15.0% Illax	
			Insulation Resistance: 10000pF~10000pF :1000MΩ min	
			220000pF~470000pF :500MΩ min	
			1000000pF :250MΩ min	
Body Strength	No abnomality such as damage.			Applied force: 19.6N
				Duration: 5 sec.
				Speed: Shall attain to specified force in 2 sec.
				\ I ,
				\♥/ 0.5R
				╵╶┶┶╴
				2.0 mm
				1.5mm (025type)
N = 1 = 1 = 1 = 1 1 = 1	At least 75% of lead surface is cov	ered with new solder.		Solder temperature: 230±5℃
Solderability				Duration: 2 ± 0.5 sec. (This test may be applical
Solderability				
Solderability				after 6 months storage
Solderability				after 6 months storage.)
olderability				after 6 months storage.)

AXIAL LEADED CERAMIC CAPACITORS

Item	Temterature Compensating(Class1)	Multilayer type Multilayer type(Characteristics:B) Multilayer type(Characteristics:F)			Test Methods and Remarks			
4 Soldering	Multilayer type Appearance : No significant abnomality							
14. Soldering	Withstanding Voltage : No abnomality	Withstanding Voltage :		Withstanding Voltage : N			erature: 270±5°C	
		Rated Voltage:16VDC		Rated Voltage:10VDC		Duration: 5±		
	Capacitance change : 8.2pF or under :Within ±0.25pF	B Capacitance change :		F Capacitance change	: Within ±20.0%	Immersed co	onditions: Inserted into t	
	10pF or over :Within ±2.5%	1200pF~22000pF(Item△J) 100000pF	: Within ±7.5% : Within ±10.0%	tanδ:	:17.5% max			ble=1.0mm diameter)
	Q:	1000000pF~1000000pF	: Within ±10.0%	4700000pF~1000000pF Insulation Resistance:		Precondition	ning: 1 hr of preconditio followed by 48±4	
	30pF or under: Q≧400+20C	tanδ: 1200pF~22000pF(Item△J)	:3.5% max	4700000pF 10000000pF	:50MΩ min :25MΩ min		-	-
	33pF or over:	100000pF 1000000pF	:5.0%max :5.0% max	Rated Voltage:16VDC		Recovery: B	under the standard ecovery for the followir	
	Q≧1000 Insulation resistance:	2200000pF~4700000pF 10000000pF	:7.5% max :12.5% max	F Capacitance change	: Within ±20.0%		andard condition after	0.
	10000MΩ min.	Insulation Resistance: 1200pF~22000pF(Item△J)	:5000MΩ min	tanδ: 100000pF	:10.0% max			ine test.
		100000pF 100000pF	:1000MΩ min :100MΩ min	2200000pF Insulation Resistance:	:15.0% max		1±2 hrs (Class 1)	
	C:Nominal Capacitance :[pF]	2200000pF	:50MΩ min	100000pF	:1000MΩ min	48	3±4 hrs(Class 2)	
		4700000pF~1000000pF	:20MΩ min	2200000pF	:125MΩ min			
		Rated Voltage:25VDC B		Rated Voltage:25VDC F				
		Capacitance change : 10000pF	: Within ±7.5%	Capacitance change tanδ:	: Within $\pm 20.0\%$			
		1000000pF tanδ:	: Within $\pm 10.0\%$	10000pF~47000pF(Item△J) Insulation Resistance:	:7.5% max			
		10000pF	:3.5%max	10000pF~47000pF(Item△J)	:1000MΩmin			
		10000000pF Insulation Resistance:	:12.5%max	Rated Voltage:35VDC				
		10000pF 10000000pF	:5000MΩ min :20MΩ min	F Capacitance change	: Within ±20.0%			
		Rated Voltage:35VDC		tanδ: 10000000pF	:17.5% max			
		B Capacitance change	: Within ±10.0%	Insulation Resistance: 10000000pF	:25MΩ min			
		tanδ:			230012 11111			
		2200000pF~4700000pF Insulation Resistance:	:7.5% max	Rated Voltage:50VDC				
		2200000pF 4700000pF	:50MΩ min :20MΩ min	Capacitance change : 10000pF~1000000pF	:Within ±20.0%			
		Rated Voltage:50VDC		tanδ: 10000pF~100000pF	:7.5% max			
		B Capacitance change :		220000pF~470000pF 1000000pF	:10.0% max :15.0% max			
		100pF~39000pF	:Within ±7.5%	Insulation Resistance:				
		47000pF~1000000pF tanδ:	:Within ±10.0%	10000pF~100000pF 220000pF~470000pF	:1000MΩ min :500MΩ min			
		100pF~39000pF 47000pF~1000000pF	:3.5% max :5.0% max	1000000pF	:250M Ω min			
		Insulation Resistance: 100pF~39000pF	:5000MΩ min					
		47000pF~100000pF	:1000MΩ min					
		220000pF 470000pF	:500MΩ min :200MΩ min					
		1000000pF	:100MΩ min					
						Duration: 30	perature: 20 to 25°C	opyl alcohol
6.Thermal Shock	Appearance : No significant abnomality				cant abnomality	Conditions	for 1 cycle	
	Withstanding Voltage : No abnomality	Withstanding Voltage :	NO ADROMAIITY	Withstanding Voltage : N	vo abnomality	Step	Temperature [°C]	Duration [min]
	Capacitance change :	Rated Voltage:16VDC B		Rated Voltage:10VDC F		1	Room temperature	Within 3
	8.2pF or under :Within ±0.5pF 10pF or over :Within ±5.0%	Capacitance change : 1200pF~22000pF(Item△J)	: Within ±12.5%	Capacitance change $tan \delta$:	: Within $\pm 30.0\%$	2	$-25\pm^{0}_{3}$	30±3
		100000pF 100000pF~1000000pF	: Within ±15.0% : Within ±15.0%	4700000pF~1000000pF Insulation Resistance:	:20.0% max	3	Room temperature	Within 3
	:8.2pF or under	tanδ:		4700000pF	:10MΩ min	4	$+85\pm_{0}^{3}$	30±3
	Q≧200+10C :10pF~30pF	1200pF~22000pF(Item△J) 100000pF	: 5.0% max : 7.5% max	10000000pF min	:5MΩ			
	Q≧275+2.5C	1000000pF 2200000pF~4700000pF	: 7.5% max : 10.0% max	Rated Voltage:16VDC		5	Room temperature	Within 3
	33pF or over:	10000000pF Insulation Resistance:	: 15.0% max	F Capacitance change	: Within ±30.0%			
	Q≧350 Insulation resistance:	1200pF~22000pF(Item△J) 100000pF	: 1000MΩ min :500MΩmin	tanδ:	: 15.0% max	Number of c	ycles: 5	
	1000MΩ min.	1000000pF	: 50MΩ min : 25MΩ min	2200000pF Insulation Resistance:	: 17.5% max		ing: 1 hr of precondition	ning at 150 +0.℃
	C:Nominal Capacitance [pF]	2200000pF 4700000pF~10000000pF	: 25MΩ min	100000pF	: 500MΩ min		followed by 48±41	
		Rated Voltage:25VDC		2200000pF	:25MΩ min		under the standard	
		B Capacitance change :		Rated Voltage:25VDC F		Recoverv: Re	covery for the followin	
		10000pF 10000000pF	: Within ±12.5% : Within ±15.0%	Capacitance change tanδ:	: Within $\pm 30.0\%$		andard condition after	
		tanδ: 10000pF	:5.0% max	10000pF~47000pF(Item△J) Insulation Resistance:	: 12.5%max		st chamber.	
		1000000pF Insulation Resistance:	:15.0% max	10000pF~47000pF(Item△J)	: 500MΩmin		±2 hrs (Class 1)	
		10000pF	:1000MΩmin	Rated Voltage:35VDC				
		10000000pF	:5MΩ min	F Capacitance change	: Within ±30.0%	48	\pm 4 hrs (Class 2)	
		Rated Voltage:35VDC B		tanδ: 10000000pF	:20.0% max			
		Capacitance change tanδ:	: Within $\pm 15.0\%$	Insulation Resistance: 10000000pF	:5MΩ min			
		2200000pF~4700000pF	:10.0% max		.019132 11111			
		Insulation Resistance: 2200000pF	:25MΩ min	Rated Voltage:50VDC				
		4700000pF	:5MΩ min	Capacitance change : 10000pF~1000000pF	:Within $\pm 30\%$			
		Rated Voltage:50VDC B		tanδ: 10000pF~100000pF	:12.5% max			
		Capacitance change : 100pF~39000pF	:Within ±12.5%	220000pF~470000pF 1000000pF	:15.0% max :17.5% max			
		47000pF~1000000pF	:Within ±12.5% :Within ±15.0%	Insulation Resistance:				
		tanδ: 100pF~39000pF	:5.0% max	10000pF~100000pF 220000pF~470000pF	:500MΩ min :250MΩ min			
					:50MΩ min	1		
		47000pF~100000pF Insulation Resistance:	:7.5% max	1000000pF	.3010122 11111			
		47000pF~100000pF Insulation Resistance:	:1000MΩ min	10000000F	.3014122 11111			
		47000pF~1000000pF Insulation Resistance: 100pF~39000pF 47000pF~100000pF 220000pF	:1000MΩ min :500MΩ min :250MΩ min		.501412 11111			
		47000pF~1000000pF Insulation Resistance: 100pF~39000pF 47000pF~100000pF	:1000MΩ min :500MΩ min		.50012211111			
		47000pF~1000000pF Insulation Resistance: 100pF~39000pF 47000pF~100000pF 220000pF 47000pF	:1000MΩ min :500MΩ min :250MΩ min :100MΩ min	10000000	.50012 1111			

Withstanding voltage is also referred to as "voltage proof" under IEC specifications. Thermal Shock is also referred to as "rapid change of temperature" under IEC specifications.

AXIAL LEADED CERAMIC CAPACITORS

		Specified Value	Test Methods and Remarks		
ltem	Temterature Compensating(Class1) Multilayer type	High Permittivity(Class2) Multilayer type(Characteristics:B) Multilayer type(Characteristics:F)			
17. Damp Heat (steady state)	Appearance : No significant abnomality Withstanding Voltage : No abnomality	Appearance : No significant abnomality Withstanding Voltage : No abnomality	Appearance : No significant abnomality Withstanding Voltage : No abnomality	emperature: 40±2°C	
()	Capacitance change :	Rated Voltage:16VDC	Rated Voltage:10VDC	Humidity: 90 to 95 % RH	
	8.2pF or under :Within ±0.5pF 10pF or over :Within ±5.0%	Capacitance change : 1200pF~22000pF(Item△J) :Within ±12.5%	F Capacitance change: Within ±30.0% tanδ:	Duration: 500^{+24}_{-0} hrs Preconditioning: 1 hr of preconditioning at 150^{+0}_{-10} °C	
	Q: :8.2pF or under	100000pF : Within ±15.0% 1000000pF~1000000pF : Within ±15.0%	4700000pE~1000000pE ·20.0% max	followed by 48 \pm 4 hrs of recovery un-	
	Q≧200+10C :10pF~30pF	tanδ: 1200pF~22000pF(Item△J) : 5.0% max 100000pF :7.5% max	1000000pr :5002 min	der the standard condition. Recovery: 24 ± 2 hrs of recovery under the standard	
	Q≧275+2.5C 33pF or over:	1000000pF : 7.5% max 2200000pF~4700000pF : 10.0% max 10000000pF : 15.0% max	Rated Voltage:16VDC	condition after the removal from test cham-	
	Q≧350 Insulation resistance:	Insulation Resistance: 1200pF~22000pF(Item△J) : 1000MΩ min	Capacitance change: Within ±30.0% tanδ:	ber. (Class 1)	
	1000MΩ min.	100000pF :500MΩ min 1000000pF :50MΩ min 2200000pF :25MΩ min	2200000pF : 17.5% max	: 1 hr of preconditioning at 150 ⁺¹⁰ °C fol- lowed by 48±4 hrs of recovery under the	
	C:Nominal Capacitance [pF]	4700000pF~1000000pF :5MΩ min		standard condition after the removal from	
		Rated Voltage:25VDC B Capacitance change:	Rated Voltage:25VDC	chamber. (Class 2)	
		10000pF : Within ±12.5% 1000000pF : Within ±15.0%	F Capacitance change: Within ±30.0%		
		tanδ: 10000pF :5.0% max 1000000pF :15.0% max	tanδ: 10000pF~47000pF(Item△J) : 12.5%max Insulation Resistance:		
		Insulation Resistance: 10000pF :1000MΩ min	10000pF~47000pF(Item△J) :500MΩmin		
		10000000pF :5MΩ min Rated Voltage:35VDC	Rated Voltage:35VDC F		
		B Capacitance change : Within ±15.0%	Capacitance change: Within ±30.0% tanδ: 10000000pF :20.0% max		
		tanδ: 2200000pF~4700000pF :10.0% max Insulation Resistance:	Insulation Resistance: 10000000pF :5MΩ min		
		2200000pF :25MΩ min 4700000pF :5MΩ min			
		Rated Voltage:50VDC	F Capacitance change : 10000pF~100000pF :Within ±30%		
		Capacitance change : 100pF~39000pF :Within ±12.5%	tanδ: 10000pF~100000pF :12.5% max		
		47000pF~100000pF :Within ±15.0% tanδ: 100pF~39000pF :5.0% max	220000pF~470000pF :15.0% max 1000000pF :17.5% max		
		47000pF~100000pF :7.5% max Insulation Resistance:	10000pr*100000pr		
		100pF~39000pF :1000MΩ min 47000pF~10000pF :500MΩ min 220000pF :250MΩ min	1000000pF :50MΩ min		
		470000pF :100MΩ min 1000000pF :50MΩ min			
18. Loading under Damp Heat	Appearance : No significant abnomality Withstanding Voltage : No abnomality	Appearance : No significant abnomality Withstanding Voltage : No abnomality	Appearance : No significant abnomality Withstanding Voltage : No abnomality	Temperature: 40±2°C	
	Capacitance change :	Rated Voltage:16VDC B	Rated Voltage:10VDC	Humidity: 90 to 95 % RH Duration: 500 $\stackrel{+24}{-0}$ hrs	
	8.2pF or under :Within ±0.75pF 10pF or over :Within ±7.5%	Capacitance change : 1200pF~22000pF(Item△J) : Within ±12.59 100000pF : Within ±15.0%	(Applied voltage: Rated voltage	
	Q: 30pF or under: Q≧100+10/3*C	1000000pF~2200000pF : Within ±15.0% 4700000pF~1000000pF : Within ±22.5%	tano: 4700000pF~1000000pF :20.0% max	Preconditioning: 1 hr of preconditioning at 150 ⁺¹⁰ ^o C followed by 48±4 hrs of recovery	
	33pF or over: Q≧200	tanδ: 1200pF~22000pF(Item△J) : 5.0% ma 100000pF : 7.5% ma:	2	under the standard condition.	
	Insulation resistance: 500MΩ min.	1000000pF : 7.5% ma: 2200000pF~4700000pF : 10.0% ma	x 10000000PF :2.5MΩ min	Recovery: 24±2 hrs of recovery under the standard condition after the removal from test cham-	
	C:Nominal Capacitance [pF]	Insulation Resistance:	F	ber. (Class 1)	
	C.Nominal Capacitance [pr]	100000pF :250MΩ mi 1000000pF :12.5MΩ mi 2200000pF :5MΩ mi		: 1 hr of preconditioning at 150 $^{+10}_{-0}~^{\circ}\text{C}$ fol-	
		4700000pF~1000000pF :2.5MΩ mi	n 2200000pF :17.5% max	lowed by 48±4 hrs of recovery under the standard condition after the removal from	
		Rated Voltage:25VDC B Capacitance change :	Insulation Resistance: 100000pF :250MΩ min	chamber. (Class 2)	
		10000pF : Within ±12.5% 10000000pF : Within ±22.5.09	6		
		tanδ: 10000pF :5.0% ma 1000000pF :22.5% ma	Rated Voltage:25VDC X F X Capacitance change: Within ±30.0%		
		Insulation Resistance: 10000pF :500MΩmir	tanδ:		
		10000000pF :2.5MΩmi Rated Voltage:35VDC	n 10000pF~47000pF(ltemΔJ) : 12.5% max Insulation Resistance: 10000pF~47000pF(ltemΔJ) :250MΩmin		
		B Capacitance change : 2200000pF ::Within ±15.0%			
		4700000pF :Within ±22.5%	F		
		2200000pF~4700000pF :10.0% max Insulation Resistance: 2200000pF :5MΩ min	tanδ:		
		4700000pF :2.5MΩ mi	Insulation Resistance: 10000000pF .20.0% max 10000000pF :25MΩ min		
		Rated Voltage:50VDC B Capacitance change :	Rated Voltage:50VDC		
		100pF~39000pF ::Within ±12.5% 47000pF~1000000pF ::Within ±15.0%	F		
		tanδ: 100pF~39000pF : 5.0% ma 47000pF~1000000pF : 7.5% ma:	Capacitance change : 10000pF~100000pF :Within ±30.0%		
		Insulation Resistance: 100pF~39000pF :500MΩ mir	10000pF~100000pF :12.5% max		
		47000pF~100000pF :250MΩ mir 220000pF :125MΩ mir	1000000pF :17.5% max		
		14/0000h			
		470000pF :25MΩ mir 1000000pF :12.5MΩ mir	Insulation Resistance: 1 10000pF~100000pF 220000pF~470000pF :125MΩ min		

Withstanding voltage is also referred to as "voltage proof" under IEC specifications.

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AXIAL LEADED CERAMIC CAPACITORS

Item	Temterature Compensating(Class1)			High Permittivity(Class2)		Test Methods and Remarks
	Multilayer type					
9. High Temperature	Appearance : No significant abnomality	Appearance : No significa	ant abnomality	Appearance : No significant abr	nomality	Temperature: 85 $\pm \frac{3}{0}$ °C
Lading Test	Withstanding Voltage : No abnomality Capacitance change :	Withstanding Voltage : No Rated Voltage:16VDC	o abnomality	Withstanding Voltage : No abno Rated Voltage:10VDC	omality	Duration: $1000 \pm \frac{48}{0}$ hrs
	8.2pF or under Within ±0.3pF	В		F Capacitance change : Within ±30.0%	6	Applied voltage: Rated voltage ×2 (Class 1)
	10pF or over :Within ±3.0% Q:	Capacitance change : 1200pF~22000pF(Item△J)	: Within ±12.5%	tanδ:		(Class 2)
	:8.2pF or under	100000pF	: Within ±15.0%	4700000pF~1000000pF : Insulation Resistance:	:20.0% max	Rated voltage × 1.5
	Q≧200+10C	1000000pF~2200000pF	: Within ±15.0%	4700000pF	:10MΩ min	(Class 2: B 220000pF~1000000pF)
	:10pF 30pF Q≧275+2.5C	4700000pF~1000000pF tanδ:	: Within $\pm 22.5\%$	10000000pF	:5MΩ min	Preconditioning: 1 hr of preconditioning at 150^{+0}_{-10} °C
	33pF or over:	1200pF~22000pF(Item△J)	: 5.0% max	Rated Voltage:16VDC		followed by 48±4 hrs of recovery
	Q≧350	100000pF	: 7.5% max	F Capacitance change :Within ±30.09	%	under the standard condition.
	Insulation resistance: 1000MΩ min.	1000000pF 2200000pF~4700000pF	: 7.5% max : 10.0% max	tanδ:		Recovery: 24±2hrs of recovery under the standard
		10000000pF	: 22.5% max	100000pF : 2200000pF :	:12.5% max :17.5% max	, , ,
	C:Nominal Capacitance [pF]	Insulation Resistance:	1000110	Insulation Resistance:		condition after the removal from test cham-
		1200pF~22000pF(Item△J) 100000pF	: 1000MΩ min :500MΩ min		500MΩ min :25MΩ min	ber. (Class1)
		100000pF	·50MO min			: 1 hr of preconditioning at 150 ⁺¹⁰ °C fol-
		2200000pF	:25MΩ min :5MΩ min	Rated Voltage:25VDC		lowed by 48±4 hrs of recovery under the
		4700000pF~1000000pF	:3M17 min	Capacitance change : Within ±30.0%	6	standard condition after the removal from
		Rated Voltage:25VDC		tanδ: 10000pF~47000pF(Item△J) :	10.0% max	chamber. (Class 2)
		B Canacitance change :		Insulation Resistance:		
		Capacitance change : 10000pF	: Within ±12.5%	10000pF~47000pF(Item△J) :	500MΩmin	
		1000000pF	: Within ±22.5%	Rated Voltage:35VDC		
		tanδ: 1000pE	-E 00/	F Capacitance change : Within ±30.0%	6	
		10000pF 10000000pF	:5.0% max :22.5% max	tanδ:		
		Insulation Resistance:		1000000pF :: Insulation Resistance:	20.0% max	
		10000pF 10000000pF	:1000MΩ min :5MΩ min	1000000pF	:5M Ω min	
		100000000	.510122 11111	Rated Voltage:50VDC		
		Rated Voltage:35VDC		F		
		B Capacitance change :		Capacitance change : 10000pF~100000pF ::Withi	in ±30.0%	
		2200000pF	:Within ±15.0%	tanδ:		
		4700000pF	:Within ±22.5%		:10.0% max :12.5% max	
		tanδ: 2200000pF~4700000pF	:10.0% max	100000pF :	:17.5% max	
		Insulation Resistance:	.10.070 1110		500MΩ min	
		2200000pF	:25MΩ min	220000pF~470000pF :2	250MΩ min	
		4700000pF	:5MΩ min	1000000pF	:50MΩ min	
		Rated Voltage:50VDC				
		B				
		Capacitance change : 100pF~39000pF	:Within ±12.5%			
		47000pF~1000000pF	:Within ±15.0%			
		tanδ:	.5.00/			
		100pF~39000pF 47000pF~1000000pF	:5.0% max :7.5% max			
		Insulation Resistance:				
		100pF~39000pF	:1000MΩ min			
		47000pF~100000pF 220000pF	:500MΩ min :250MΩ min			
		470000pF	:100MΩ min			
		100000pF	:50MΩ min			
		1				

Note on standard condition: "standard condition" referred to herein is defined as follows:

5 to 35°C of temperature, 45 to 85% relative humidity, and 86 to 106kPa of air pressure.

When there are questions concerning measurement results: In order to provide correlation data, the test shall be conducted under condition of $20\pm2^{\circ}$ C of temperature, 60 to 70% relative humidity, and 86 to 106kPa of air pressure. Unless otherwise specified, all the tests are conducted under the "standard condition." Withstanding voltage is also referred to as "voltage proof" under IEC specifications.

Precautions on the use of Axiel Leaded Ceramic Capacitors

Stages	Precautions	Technical considerations
Circuit Design	 Verification of operating environment, electrical rating and performance 1. A malfunction in medical equipment, spacecraft, nuclear reactors, etc. may cause serious harm to human life or have severe social ramifications. As such, any capacitors to be used in such equipment may require higher safety and/or reliability considerations and should be clearly differentiated from components used in general purpose applications. Verification of Rated voltage (DC rated voltage) 1. The operating voltage for capacitors must always be lower than their rated values. If an AC voltage is loaded on a DC voltage, the sum of the two peak voltages should be lower than the rated value of the capacitor chosen. For a circuit where both an AC and a pulse voltage may be present, the sum of their peak voltages should also be lower than the capacitor's rated voltage. 2. Even if the applied voltage is lower than the rated value, the reliability of capacitors might be reduced if either a high frequency AC voltage or a pulse voltage having rapid rise time is present in the circuit. Self-generated heat (Verification of Temperature) 1. If the capacitor specified only for DC use are used in AC or pulse circuits, the AC or a pulse current can generate heat inside the capacitor so the self-generated temperature rise should be limited to within 20°C. The surface temperature including self -generated heat should not exceed the maximum operating temperature of +85°C. 	 1-1. When an AC or a pulse voltage is applied to capacitors specified for DC use, even if the voltage is less than the rated voltage, the AC current or pulse current running through the capacitor will cause the capacitor to self-generate heat because of the loss characteristics. The amount of heat generated depends on the dielectric materials used, capacitance applied voltage, frequency, voltage waveform, etc. The surface temperature change due to emitted heat which differs by capacitor shape or mounting method. Please contact Taiyo Yuden with any questions regarding emitted heat levels in you particular application. It is recommend the temperature rise be measured in the actual circuit to be used. 1-2. For capacitors, the voltage and frequency relationship is generally determined by peak voltage at low frequencies, and by self-generated heat at high frequencies. (Refet to the following curve.)
	 Operating Environment precautions Capacitors should not be used in the following environments: (1)Environmental conditions to avoid 	Frequency
	a. exposure to water or salt water.b. exposure to moisture or condensation.c. exposure to corrosive gases (such as hydrogen sulfide, sulfurous acid, chlorine, and ammonia)	
. PCB Design	 When capacitors are mounted onto a PC board, hole dimensions on the board should match the lead pitch of the component, if not it will cause breakage of the terminals or cracking of terminal roots covered with resin as excess stress travels through the terminal legs. As a result, humidity resistance performance would be lost and may lead to a reduction in insulation resistance and cause a withstand voltage failure. 	
8. Considerations for automatic insertion	 Adjustment Automatic Insertion machines (leaded components) When inserting capacitors in a PC board by auto-insertion machines the impact load imposed on the capacitors should be minimized to prevent the leads from chucking or clinching. 	 When installing products, care should be taken not to apply distortion stress as it may deform the products. Our company recommends the method to place the lead with fewer loads that join the product.

Precautions on the use of Axiel Leaded Ceramic Capacitors

Stages	Precautions	Technical considerations
4. Soldering	 Selection of Flux When soldering capacitors on the board, flux should be applied thinly and evenly. Flux used should be with less than or equal to 0.1 wt% (equivalent to Chroline) of halogenated content. Flux having a strong acidity content should not be applied. When using water-soluble flux, special care should be taken to properly clean the boards. Wave Soldering 	 Flux is used to increase solderability in wave soldering, but if too much is applied, a large amount of flux gas may be emitted and may detrimentally affect solderability. To minimize the amount of flux applied, it is recommended to use a flux-bubbling system. With too much halogenated substance (Chlorine, etc.) content is used to activate the flux, an excessive amount of residue after soldering may lead to corrosion of the terminal elec- trodes or degradation of insulation resistance on the surface of the capacitors. Since the residue of water-soluble flux is easily dissolved by water content in the air, the residue on the surface of capacitors in high humidity conditions may cause a degradation of insulation resistance and therefore affect the reliability of the components. The clean- ing methods and the capability of the machines used should also be considered carefully when selecting water-soluble flux.
	 Temperature, time, amount of solder, etc. are specified in accordance with the following recommended conditions. Do not immerse the entire capacitor in the flux during the soldering operation. Only solder the lead wires on the bot- tom of the board. 	 If capacitors are used beyond the range of the recommended conditions, heat stresses may cause cracks inside the capacitors, and consequently degrade the reliability of the capacitors. When the capacitors are dipped in solder, some soldered parts of the capacitor may melt due to solder heat and cause short-circuits or cracking of the ceramic material. Deteriora- tion of the resin coating may lower insulation resistance and cause a reduction of with- stand voltage.
	 Recommended conditions for using a soldering iron: Put the soldering iron on the land-pattern. Soldering iron's temperature - below 350°C Duration - 3 seconds or less Numbers of times - 1 times The soldering iron should not directly touch the capacitor. 	 If products are used beyond the range of the recommended conditions,heat stress may deform the products,and consequently degrade the reliability of the products.
5. Cleaning	 Board cleaning 1. When cleaning the mounted PC boards, make sure that cleaning conditions are consistent with prescribed usage conditions. 	 The resin material used for the outer coating of capacitors is occasionally a wax substance for moisture resistance which can easily be dissolved by some solutions. So before cleaning, special care should be taken to test the component's vulnerability to the solutions used. When using water-soluble flux please clean the PCB with purified water sufficiently and dry thoroughly at the end of the process. Insufficient washing or drying could lower the reliability of the capacitors.
6. Post-cleaning-process	 Application of resin molding, etc. to the PCB and components. Please contact your local Taiyo Yuden sales office before performing resin coating or molding on mounted capacitors. Please verify on the actual application that the coating process will not adversely affect the component quality. 	 1-1. The thermal expansion and coefficient of contraction of the molded resin are not necessarily matched with those of the capacitor. The capacitors may be exposed to stresses due to thermal expansion and contraction during and after hardening. This may lower the specified characteristics and insulation resistance or cause reduced withstand voltage by cracking the ceramic or separating the coated resin from the ceramics. 1-2. With some types of mold resins, the resin's decomposition gas or reaction gas may remain inside the resin during the hardening period or while left under normal conditions, causing a deterioration of the capacitor's performance. 1-3. Some mold resins may have poor moisture proofing properties. Please verify the contents of the resins before they are applied. 1-4. Please contact Taiyo Yuden before using if the hardening process temperature of the mold resins is higher than the operating temperature of the capacitors.
7. Handling	 Mechanical considerations Be careful not to subject the capacitors to excessive mechanical shocks. Withstanding voltage failure may result. If ceramic capacitors are dropped onto the floor or a hard surface they should not be used. 	 Because the capacitor is made of ceramic, mechanical shocks applied to the board may damage or crack the capacitors. Ceramic capacitors which are dropped onto the floor or a hard surface may develop defects and have a higher risk of failure over time.
8. Storage conditions	 Storage To maintain the solderability of terminal electrodes and to keep the packaging material in good condition, care must be taken to control temperature and humidity in the storage area. Humidity should especially be kept as low as possible. Recommended conditions: Ambient temperature Below 40 °C Humidity Below 70% RH. Products should be used within 6 months after delivery. After the above period, the solderability should be checked before using the capacitors. Capacitors should not be kept in an environment filled with decomposition gases such as (sulfurous hydrogen, sulfurous acid, chlorine, ammonia, etc.) Capacitors should not be kept in a location where they may be exposed to moisture, condensation or direct sunlight. 	 Under high temperature/high humidity conditions, the decrease in solderability due to the oxidation of terminal electrodes and deterioration of taping and packaging char- acteristics may be accelerated.